News Release

Unisem Announces Participation in Upcoming April and May Conferences

Sunnyvale, 14 April 2015 – Unisem, a global provider of semiconductor assembly and test services, today announced that it will be exhibiting at the following upcoming conferences:

- MEMS Industry Group's MEMS Technical Congress 2015 on May 6-7 in Boston, MA.
- MEMS Journal's Automotive Sensors and Electronics Expo 2015 on May 20 in Detroit, MI.
- MEPTEC MEMS Tech Symposium on May 20 in San Jose, CA.
- MEPTEC Internet of Things Symposium on May 21 in San Jose, CA.

The company will also be participating but not exhibiting at the following conferences:

- iMAPS MINaPAD Forum 2015 on April 22-23 in Grenoble, France
- Semicon Southeast Asia on April 22-24 in Penang, Malaysia
- ECTC 2015 on May 26-29 in San Diego, CA

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; Batam, Indonesia; and Sunnyvale, USA. Unisem is headquartered in Kuala Lumpur, Malaysia.

For additional information on Unisem, please visit: www.unisemgroup.com. Follow Unisem on Twitter and on Linkedin.

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